

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT8368601

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
NST TECHNOLOGY CO., LTD.	12/26/2023
RECEIVING PARTY DATA	
Name:	SHANGHAI AIMIC MEDICAL ELECTRONICS CO.
Street Address:	UNIT 67, 1/F, BUILDING 27, NO. 487 TIANLIN ROAD, XUHUI DISTRICT
City:	SHANGHAI
State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	9408018
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	0118/0760M
NAME OF SUBMITTER:	MADELAINE STITES
SIGNATURE:	/Madelaine Stites/
DATE SIGNED:	01/08/2024
Total Attachments: 3	
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PATENT ASSIGNMENT

THIS ASSIGNMENT is made this 26th day of December, 2023

BETWEEN:

- (1) NST TECHNOLOGY CO, LTD., a Chinese company having its place of business at Room 1408, No. 600 Luban Road, Huangpu District, Shanghai, China (hereinafter referred to as "the Assignor");
- (2) SHANGHAI AIMIC MEDICAL ELECTRONICS CO., LTD (聚交芯创医疗电子(上海)有限公司), a Chinese company with registration No. 91310104MAD62HP614 and having its place of business at Unit 67, 1/F, Building 27, No. 487 Tianlin Road, Xuhui District, Shanghai, China (hereinafter referred to as "the Assignee").

WHEREAS:

- (A) The Assignor is the proprietor of the patent set out in the Schedule hereto (hereinafter referred to as "the Patent") relating to the inventions contained therein (hereinafter referred to as "the Inventions").
- (B) The Assignor has agreed to assign the Patent Applications and the Inventions to the Assignee for the consideration set out below.

IT IS AGREED AS FOLLOWS:

1. In consideration of the sum of One Dollar (\$1.00) now paid to the Assignor by the Assignee (receipt of which is hereby acknowledged by the Assignor) the Assignor hereby assigns to the Assignee all right title and interest in the Patent Applications and the Inventions referred to above, including all rights arising therefrom, including the right to file further applications in any country in respect of the Inventions, and including the right to bring proceedings for any previous infringement of the rights assigned by this Assignment.
2. The Assignor shall, at the expense of the Assignee, execute all such documents and do all such things as may reasonably be required for the Assignee (or the nominee of the Assignee) to enjoy the full benefit of the property and rights hereby assigned, including (if required to do so by the Assignee) applying for patents in the name of the Assignor.

IN WITNESS of which the parties have executed this Assignment the day and year first above written.

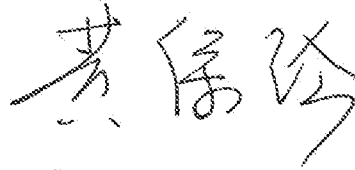
SCHEDULE

The Patent included in the assignment is the following:

Country	Title	Patent No.	Patent Date
US	BUFFER LAYER ON SILICON CARBIDE SUBSTRATE, AND METHOD FOR FORMING BUFFER LAYER	9408018	2 August 2016

Signed for and on behalf of
the Assignor by

HUANG, Baogian Director
(Name & Position)



(Signature)

Signed for and on behalf of
the Assignee by

CHEN, Jin General Manager
(Name & Position)



(Signature)